

Title (en)  
THERMALLY CURED UNDERLAYER FOR LITHOGRAPHIC APPLICATION

Title (de)  
THERMISCH GEHÄRTETE UNTERSCHICHT FÜR DIE LITHOGRAPHIE

Title (fr)  
SOUS-COUCHE DURCIE THERMIQUEMENT POUR APPLICATION LITHOGRAPHIQUE

Publication  
**EP 1373331 A2 20040102 (EN)**

Application  
**EP 02733834 A 20020307**

Priority  
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• US 27552801 P 20010313

Abstract (en)  
[origin: WO02073307A2] Thermally cured undercoat for use in lithography of a thermally cured composition comprising a hydroxyl-containing polymer, an amino cross-linking agent and a thermal acid generator, wherein the hydroxyl containing polymer is a polymer comprising units m, n and o of the formula (I) wherein R<1> is H or methyl; R<2> is a substituted or unsubstituted C6-C14 aryl acrylate or C6-C14 aryl methacrylate group wherein the substituted groups may be phenyl, Cl-4 alkyl or C1-4 alkoxy; R<3> is a hydroxyl functionalized Cl-C8 alkyl acrylate, methacrylate or C6-C14 aryl group, R<4> is a C1-C10 linear or branched alkylene; p is an integer of from 1 to 5 with the proviso that there are no more than thirty carbon atoms in the [-R<4>O-]<sub>p</sub>; R<5> is a Cl-C10 linear, branched or cyclic alkyl, substituted or unsubstituted C6-Cl4 aryl, or substituted or unsubstituted C7-Cl5 alicyclic hydrocarbon; and m is about 40 to 70, n is about 15 to 35 and o is about 15 to 25.

IPC 1-7  
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IPC 8 full level  
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